

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2851060

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIDEAKI TAKAHASHI	05/08/2014
TATSUYA KARASAWA	05/08/2014
YO SAKAMOTO	05/08/2014
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14351457
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DATE SIGNED:	05/12/2014
Total Attachments: 2	
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ASSIGNMENT

For value received, we, Hideaki TAKAHASHI; Tatsuya KARASAWA; and Yo SAKAMOTO having post office address at c/o FUJI ELECTRIC CO., LTD., 1-1 Tanabeshinden, Kawasaki-ku, Kawasaki-shi 210-9530, Japan hereby sell, assign and transfer to FUJI ELECTRIC CO., LTD. corporation existing under the laws of Japan located at 1-1 Tanabeshinden, Kawasaki-ku, Kawasaki-shi, 210-9530, Japan and its successors, assigns, and legal representatives the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD described in application for Letters Patent of the United States, Serial No.

14/351,457 Filed April 11, 2014 and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I/We have full right so to do, and agree that I/We will communicate to said Company or its representatives any facts known to me/us respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature Hideaki Takahashi Date May 8 2014
Hideaki TAKAHASHI

Signature Tatsuya Karasawa Date May 8 2014
Tatsuya KARASAWA

Signature Yo Sakamoto Date May 8 2014
Yo SAKAMOTO